

SNx4HC251 3 ステート出力、データ・セクタ / マルチプレクサ

1 特長

- 'HC151 の 3 ステート・バージョン
- 幅広い動作電圧範囲: 2V~6V
- 大電流の 3 ステート出力インターフェイスはシステム・バスと直接接続でき、または最大 15 個の LSTTL 負荷を駆動できます。
- 低消費電力、 I_{CC} : 80 μ A 以下
- $t_{pd} = 9$ ns (標準値)
- 5V で ± 6 mA の出力駆動能力
- 低い入力電流: 最大 1 μ A
- パラレル / シリアル変換を実行
- 相補出力により、非反転および反転データを出力

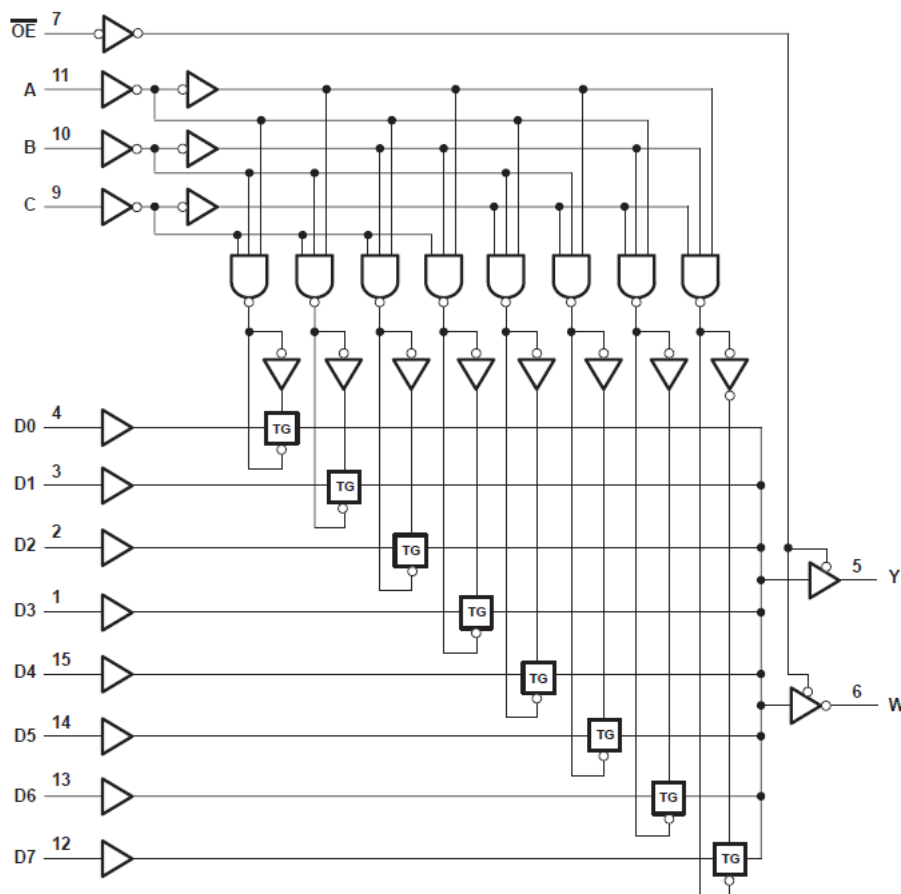
2 概要

SNx4HC251 は、8 つのデータ源の 1 つを選択するためのフル・バイナリ・デコード機能とストロブ制御付き相補 3 ステート出力を備えたデータ・セクタ / マルチプレクサです。

製品情報

部品番号	パッケージ ⁽¹⁾	本体サイズ (公称)
SN74HC251D	SOIC (16)	9.90mm × 3.90mm
SN74HC251DB	SSOP (16)	6.20mm × 5.30mm
SN74HC251N	PDIP (16)	19.31mm × 6.35mm
SN74HC251NS	SO (16)	6.20mm × 5.30mm
SN74HC251PW	TSSOP (16)	5.00mm × 4.40mm
SN54HC251J	CDIP (16)	24.38mm × 6.92mm
SNJ54HC251FK	LCCC (20)	8.89mm × 8.45mm

(1) 利用可能なパッケージについては、このデータシートの末尾にある注文情報を参照してください。



ここに示すピン番号は D、DB、J、N、NS、PW、W の各パッケージのものです。

機能ブロック図



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3 Revision History

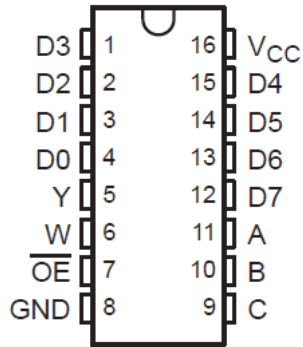
資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

Changes from Revision E (September 2003) to Revision F (February 2022)

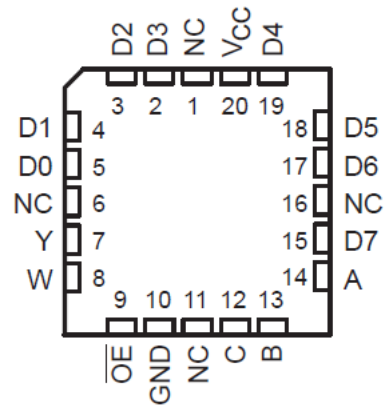
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- 最新のデータシート規格を反映するように、文書全体にわたって表、図、相互参照の採番方法を更新..... 1

4 Pin Configuration and Functions



J, D, DB, N, NS, or PW Package
16-Pin CDIP, SOIC, SSOP, PDIP, SO, or TSSOP
Top View



NC - No internal connection

FK Package
20-Pin LCCC
Top View

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V _{CC}	Supply voltage range	-0.5	7	V
I _{IK}	Input clamp current ⁽²⁾	V _I < 0 or V _I > V _{CC}	±20	mA
I _{OK}	Output clamp current ⁽²⁾	V _O < 0 or V _O > V _{CC}	±20	mA
I _O	Continuous output current	V _O = 0 to V _{CC}	±35	mA
	Continuous current through V _{CC} or GND		±70	mA
T _J	Junction temperature		150	°C
T _{stg}	Storage temperature	-65	150	°C

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

5.2 Recommended Operating Conditions⁽¹⁾

		SN54HC251			SN74HC251			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage	2	5	6	2	5	6	V
V _{IH}	High-level input voltage	V _{CC} = 2 V	1.5		1.5			V
		V _{CC} = 4.5 V	3.15		3.15			
		V _{CC} = 6 V	4.2		4.2			
V _{IL}	Low-level input voltage	V _{CC} = 2 V		0.5		0.5		V
		V _{CC} = 4.5 V		1.35		1.35		
		V _{CC} = 6 V		1.8		1.8		
V _I	Input voltage	0		V _{CC}	0		V _{CC}	V
V _O	Output voltage	0		V _{CC}	0		V _{CC}	V
Δt/Δv	Input transition rise/fall time	V _{CC} = 2 V		1000		1000		ns
		V _{CC} = 4.5 V		500		500		
		V _{CC} = 6 V		400		400		
T _A	Operating free-air temperature	-55		125	-40		85	°C

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).

5.3 Thermal Information

THERMAL METRIC ⁽¹⁾		D (SOIC)	DB (SSOP)	N (PDIP)	NS (SO)	PW (TSSOP)	UNIT
		16 PINS	16 PINS	16 PINS	16 PINS	16 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	73	82	67	64	108	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC package thermal metrics](#) application report.

5.4 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS ⁽¹⁾	V _{CC} (V)	T _A = 25°C			SN54HC251		SN74HC251		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	I _{OH} = -20 μA	2	1.9	1.998		1.9		1.9	V	
		4.5	4.4	4.499		4.4		4.4		
		6	5.9	5.999		5.9		5.9		
	I _{OH} = -6 mA	4.5	3.98	4.3		3.7		3.84		
	I _{OH} = -7.8 mA	6	5.48	5.8		5.2		5.34		
V _{OL}	I _{OL} = 20 μA	2		0.002	0.1		0.1	0.1	V	
		4.5		0.001	0.1		0.1	0.1		
		6		0.001	0.1		0.1	0.1		
	I _{OL} = 6 mA	4.5		0.17	0.26		0.4	0.33		
	I _{OL} = 7.8 mA	6		0.15	0.26		0.4	0.33		
I _I	V _I = V _{CC} or 0	6		±0.1	±100		±1000	±1000	nA	
I _{OZ}	V _o = V _{CC} or 0	6		±0.01	±0.5		±10	±5	μA	
I _{CC}	V _I = V _{CC} or 0, I _o = 0	6			8		160	80	μA	
C _i		2 to 6		3	10		10	10	pF	

(1) V_I = V_{IH} or V_{IL}, unless otherwise noted.

5.5 Switching Characteristics

over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see [6-1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} (V)	T _A = 25°C			SN54HC251		SN74HC251		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{pd}	A, B, or C	W or Y	2		58	205		300		256	ns
			4.5		21	41		60		51	
			6		19	35		51		44	
	Any D	W or Y	2		44	195		283		244	
			4.5		17	39		57		49	
			6		15	33		48		41	
t _{en}	OE	W or Y	2		30	145		210		181	ns
			4.5		10	29		42		36	
			6		9	25		36		31	
t _{dis}	OE	W or Y	2		25	195		283		244	ns
			4.5		15	39		57		49	
			6		14	33		48		41	
t _t		W or Y	2		20	75		110		95	ns
			4.5		8	15		22		19	
			6		6	13		19		16	

5.6 Switching Characteristics

over recommended operating free-air temperature range, $C_L = 150 \text{ pF}$ (unless otherwise noted) (see [Figure 6-1](#))

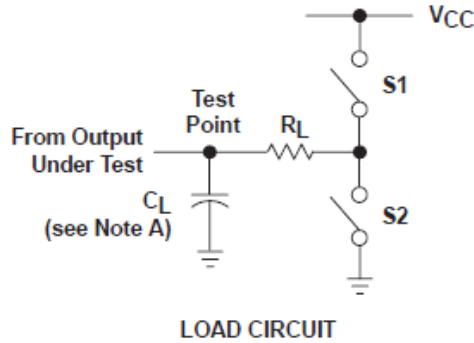
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} (V)	$T_A = 25^\circ\text{C}$			SN54HC251		SN74HC251		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A, B, or C	W or Y	2		72	300		450		375	ns
			4.5		25	60		90		75	
			6		22	52		77		65	
	Any D	W or Y	2		59	300		450		375	
			4.5		21	60		90		75	
			6		18	52		77		65	
t_{en}	\overline{OE}	W or Y	2		50	230		340		285	ns
			4.5		17	46		68		57	
			6		15	40		58		50	
t_t		W or Y	2		45	210		315		265	ns
			4.5		17	42		63		53	
			6		13	36		53		45	

5.7 Operating Characteristics

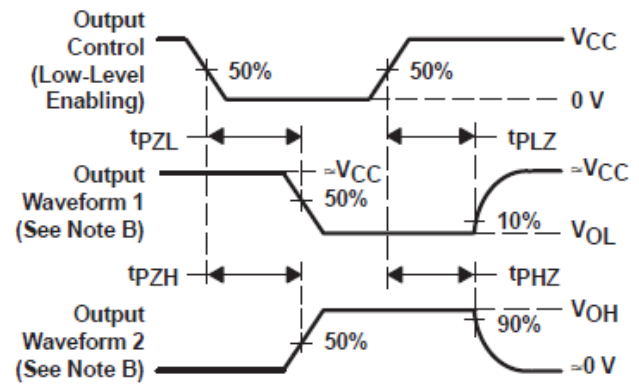
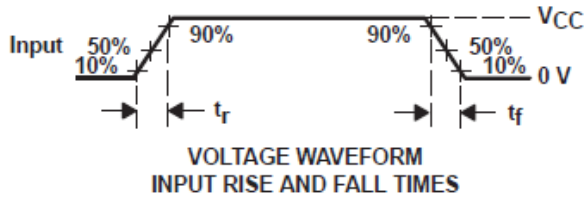
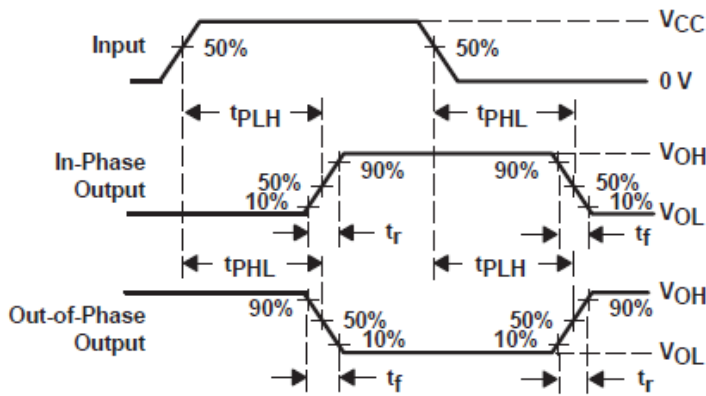
$T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	No load	70	pF

6 Parameter Measurement Information



PARAMETER	R_L	C_L	S1	S2
t_{en}	1 k Ω	50 pF or 150 pF	Open	Closed
			Closed	Open
t_{dis}	1 k Ω	50 pF	Open	Closed
			Closed	Open
t_{pd} or t_t	—	50 pF or 150 pF	Open	Open



- NOTES: A. C_L includes probe and test-fixture capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_O = 50 \Omega$, $t_r = 6$ ns, $t_f = 6$ ns.
 D. The outputs are measured one at a time with one input transition per measurement.
 E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 F. t_{PZL} and t_{PZH} are the same as t_{en} .
 G. t_{PLH} and t_{PHL} are the same as t_{pd} .

6-1. Load Circuit and Voltage Waveforms

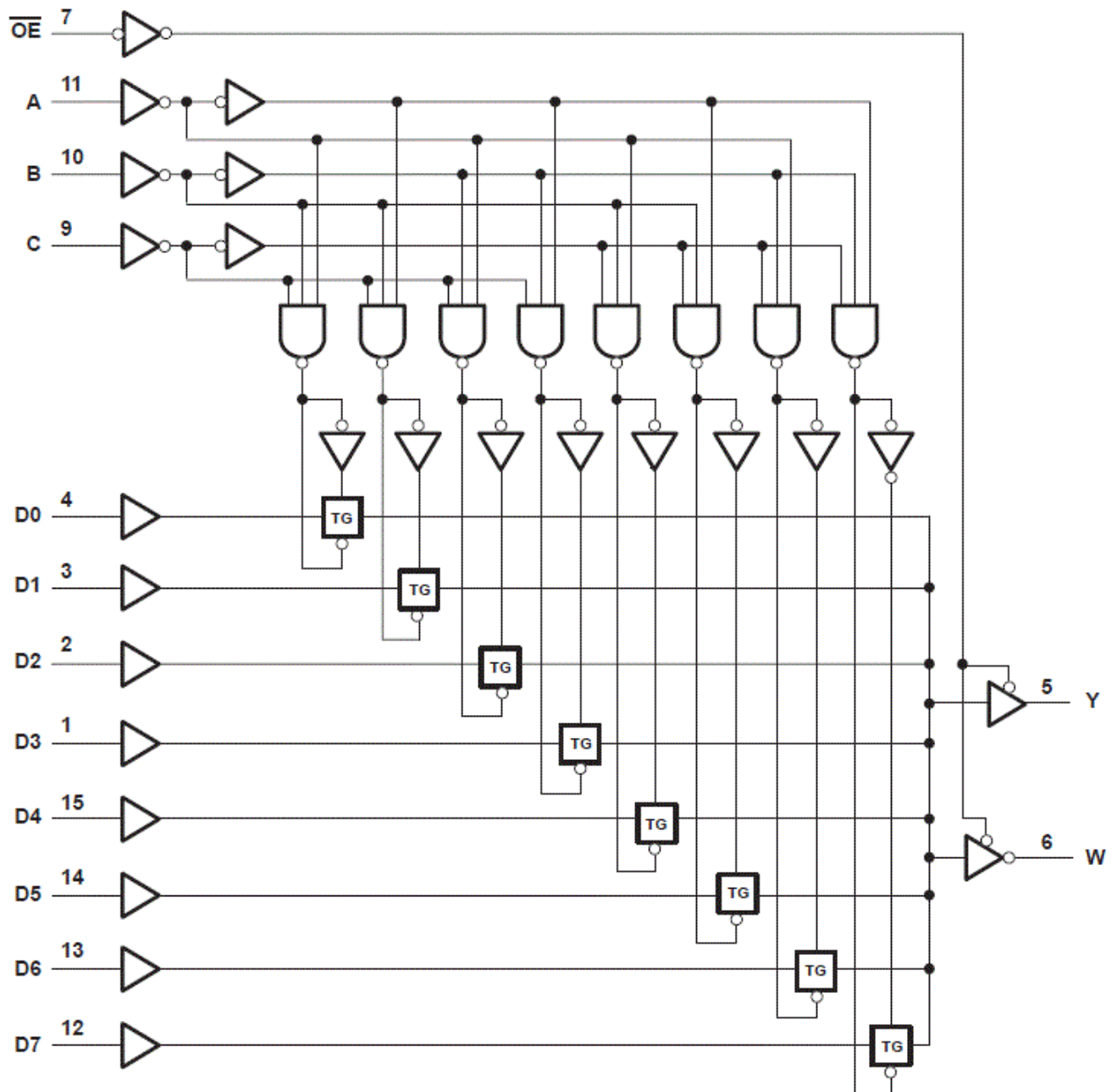
7 Detailed Description

7.1 Overview

These data selectors/multiplexers contain full binary decoding to select 1-of-8 data sources and feature strobe-controlled complementary 3-state outputs.

The 3-state outputs can interface with and drive data lines of bus-organized systems. With all but one of the common outputs disabled (in the high-impedance state), the low impedance of the single enabled output drives the bus line to a high or low logic level. Both outputs are controlled by the output-enable (\overline{OE}) input. The outputs are disabled when \overline{OE} is high.

7.2 Functional Block Diagram



Pin numbers shown are for the D, DB, J, N, NS, PW, and W packages.

7.3 Device Functional Modes

表 7-1. Function Table⁽¹⁾

INPUTS			OUTPUTS		
SELECT			OE	Y	W
C	B	A			
X	X	X	H	Z	Z
L	L	L	L	D0	$\overline{D0}$
L	L	H	L	D1	$\overline{D1}$
L	H	L	L	D2	$\overline{D2}$
L	H	H	L	D3	$\overline{D3}$
H	L	L	L	D4	$\overline{D4}$
H	L	H	L	D5	$\overline{D5}$
H	H	L	L	D6	$\overline{D6}$
H	H	H	L	D7	$\overline{D7}$

(1) D0, D1 . . . D7 = the level of the respective D input.

8 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the *Recommended Operating Conditions*. Each V_{CC} terminal should have a good bypass capacitor to prevent power disturbance. A 0.1- μF capacitor is recommended for this device. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. The 0.1- μF and 1- μF capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results.

9 Layout

9.1 Layout Guidelines

When using multiple-input and multiple-channel logic devices inputs must not ever be left floating. In many cases, functions or parts of functions of digital logic devices are unused; for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such unused input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. All unused inputs of digital logic devices must be connected to a logic high or logic low voltage, as defined by the input voltage specifications, to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally, the inputs are tied to GND or V_{CC} , whichever makes more sense for the logic function or is more convenient.

10 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

10.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

10.2 サポート・リソース

[TI E2E™ サポート・フォーラム](#)は、エンジニアが検証済みの回答と設計に関するヒントをエキスパートから迅速かつ直接得ることができる場所です。既存の回答を検索したり、独自の質問をしたりすることで、設計に必要な支援を迅速に得ることができます。

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10.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.

すべての商標は、それぞれの所有者に帰属します。

10.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

10.5 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
85125012A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	85125012A SNJ54HC 251FK
8512501EA	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8512501EA SNJ54HC251J
SN54HC251J	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54HC251J
SN54HC251J.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54HC251J
SN74HC251D	Obsolete	Production	SOIC (D) 16	-	-	Call TI	Call TI	-40 to 85	HC251
SN74HC251DBR	Active	Production	SSOP (DB) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC251
SN74HC251DBR.A	Active	Production	SSOP (DB) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC251
SN74HC251DR	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	-40 to 85	HC251
SN74HC251DR.A	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC251
SN74HC251DRG4	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC251
SN74HC251DRG4.A	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC251
SN74HC251DT	Obsolete	Production	SOIC (D) 16	-	-	Call TI	Call TI	-40 to 85	HC251
SN74HC251N	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74HC251N
SN74HC251N.A	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74HC251N
SN74HC251NSR	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC251
SN74HC251NSR.A	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC251
SN74HC251PW	Obsolete	Production	TSSOP (PW) 16	-	-	Call TI	Call TI	-40 to 85	HC251
SN74HC251PWR	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	-40 to 85	HC251
SN74HC251PWR.A	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC251
SN74HC251PWR.B	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC251
SN74HC251PWT	Obsolete	Production	TSSOP (PW) 16	-	-	Call TI	Call TI	-40 to 85	HC251
SNJ54HC251FK	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	85125012A SNJ54HC 251FK
SNJ54HC251FK.A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	85125012A SNJ54HC 251FK

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SNJ54HC251J	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8512501EA SNJ54HC251J
SNJ54HC251J.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8512501EA SNJ54HC251J

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54HC251, SN74HC251 :

- Catalog : [SN74HC251](#)

- Military : [SN54HC251](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC251DBR	SSOP	DB	16	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74HC251DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC251DRG4	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC251NSR	SOP	NS	16	2000	330.0	16.4	8.45	10.55	2.5	12.0	16.2	Q1
SN74HC251NSR	SOP	NS	16	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1
SN74HC251PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC251DBR	SSOP	DB	16	2000	353.0	353.0	32.0
SN74HC251DR	SOIC	D	16	2500	353.0	353.0	32.0
SN74HC251DRG4	SOIC	D	16	2500	353.0	353.0	32.0
SN74HC251NSR	SOP	NS	16	2000	353.0	353.0	32.0
SN74HC251NSR	SOP	NS	16	2000	353.0	353.0	32.0
SN74HC251PWR	TSSOP	PW	16	2000	353.0	353.0	32.0

TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
85125012A	FK	LCCC	20	55	506.98	12.06	2030	NA
SN74HC251N	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC251N	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC251N.A	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC251N.A	N	PDIP	16	25	506	13.97	11230	4.32
SNJ54HC251FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54HC251FK.A	FK	LCCC	20	55	506.98	12.06	2030	NA

GENERIC PACKAGE VIEW

FK 20

LCCC - 2.03 mm max height

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



4229370VA\

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.



PACKAGE OUTLINE

NS0016A

SOP - 2.00 mm max height

SOP



4220735/A 12/2021

NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.

EXAMPLE BOARD LAYOUT

NS0016A

SOP - 2.00 mm max height

SOP



4220735/A 12/2021

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

NS0016A

SOP - 2.00 mm max height

SOP



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:7X

4220735/A 12/2021

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.



4220204/A 02/2017

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4220204/A 02/2017

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220204/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

DB0016A



PACKAGE OUTLINE

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



4220763/A 05/2022

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-150.

EXAMPLE BOARD LAYOUT

DB0016A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220763/A 05/2022

NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DB0016A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220763/A 05/2022

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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郵送先住所：Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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